



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Benfer, David W	Contact Title	Prod Compliance Engineer		
Company Unique ID	TE Connectivity	Response Date	2017-03-21	Contact Email	dave.benfer@te.com				
Contact Phone Number	717-986-3725								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	1-1775801-2	Amount	2696.05	Version	-	Identity			
Manufacturer Item Name	PCI EXPRESS 36P(2.3)(15")BL ACK	Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EUroHS-0508	Product(s) meets EU RoHS requirement without any exemptions								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-0616	REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH								
Complex Article Description	REACH Candidate Substances of Very High Concern according to Once an Article Always an Article are Not Yet Reviewed								
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Material	1	CONTACT PLATING (Sn)				1.0	2.10022295	mg	
Substance	2	Tin	Supplier	7440-31-5	99.9	1.0	2.09812	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.00210022	mg	
Material	1	BOARDLOCK PLATING (Ni)				1.0	0.4205838	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.9	1.0	0.42016	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	4.2058E-4	mg	
Material	1	HOUSING				1.0	2099.9964818	mg	
Substance	2	Antimony oxide (Sb2O3)	Supplier	1309-64-4	3.0	1.0	62.99989	mg	
Substance	2	Glass, oxide, chemicals	Supplier	65997-17-3	40.0	1.0	839.99859	mg	
Substance	2	Benzene, ethenyl-, homopolymer, brominated	Supplier	88497-56-7	7.0	1.0	146.99975	mg	
Substance	2	Hexanedioic acid, polymer with 1,4-butanediamine	Supplier	50327-77-0	50.0	1.0	1049.99824	mg	
Material	1	BOARDLOCK				1.0	140.69876135	mg	
Substance	2	Zinc	Supplier	7440-66-6	33.0	1.0	46.43059	mg	
Substance	2	Iron	Supplier	7439-89-6	0.07	1.0	0.09848913	mg	
Substance	2	Copper	Supplier	7440-50-8	66.83	1.0	94.02898	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.1407	mg	
Material	1	CONTACT PLATING (Ni)				1.0	4.03059475	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.9	1.0	4.02656	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.00403059	mg	
Material	1	BOARDLOCK PLATING (Sn)				1.0	0.700973	mg	
Substance	2	Tin	Supplier	7440-31-5	99.9	1.0	0.70027	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	7.0097E-4	mg	
Material	1	CONTACT				1.0	447.73032745	mg	

Substance	2	Copper	Supplier	7440-50-8	92.35	1.0	413.47896	mg	
Substance	2	Iron	Supplier	7439-89-6	0.1	1.0	0.44773	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.35	1.0	1.56706	mg	
Substance	2	Zinc	Supplier	7440-66-6	0.2	1.0	0.89546	mg	
Substance	2	Tin	Supplier	7440-31-5	7.0	1.0	31.34112	mg	
Material	1	CONTACT PLATING (Au)				1.0	0.3720549	mg	
Substance	2	Gold	Supplier	7440-57-5	100.0	1.0	0.37205	mg	